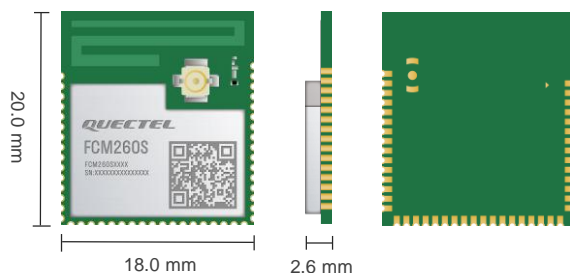


Quectel FCM260S

Wi-Fi 6 & BLE 5.4

Compact LCC Package



FCM260S is a cutting-edge MCU Wi-Fi and BLE module launched by Quectel. It boasts an ARM Cortex-M4 processor with a frequency of up to 180 MHz and supports IEEE 802.11b/g/n/ax protocol of single band (2.4 GHz) and BLE 5.4. It complies with the WPA, WPA2 and WPA3 security standards, and supports AES128/256/192, SHA256/384/512, HMAC, RNG, CRC, SHA3, AES-GCM, CMAC, TRNG, RSA, ECC, secure boot encryption algorithm.

FCM260S is in an LCC form factor with a compact package size of 20.0 mm × 18.0 mm × 2.6 mm, which optimizes the size and cost for end-products and is compatible with diverse designs. It features built-in 672 KB SRAM and 8 MB flash, ensuring efficient performance. It also offers optional PSRAM expansion for more complex applications.

FCM260S supports up to 35 GPIOs and one JTAG/SWD, which can be multiplexed for various interfaces including UART, SPI, I2C, SDIO, I2S, PWM, ADC, DAC, SSI, etc. in QuecOpen® solution. The module supports PCB antenna/1st generation RF coaxial connector/pin antenna. And it has ultra-low power consumption and features a built-in BPF filter, enhancing the module's performance in harmonic suppression and anti-interference. It is widely used in ultra-low power consumption fields such as door locks, curtains, IPCs and single-phase switches, and provides flexibility and versatility for a range of applications, especially in smart homes and industrial IoT scenarios.



Key Features

- ✓ 2.4 GHz, Wi-Fi 6.0 and BLE 5.4
- ✓ 672 KB SRAM and 8 MB flash
- ✓ PSRAM expansion (optional)
- ✓ BPF filter
- ✓ Supports UART, SPI, I2C, SDIO, I2S, PWM, ADC, DAC, SSI, etc. under multiplexing
- ✓ Operating temperature range: -40 °C to +85 °C
- ✓ PCB antenna/1st generation RF coaxial connector/pin antenna (optional)



IEEE 802.11
b/g/n/ax



BLE 5.4



Ultra-low Power
Consumption



LCC Package



Operating Temperature
Range: -40 °C to +85 °C



Multiple
Interfaces



Large Memory



Compact Size

Wi-Fi 6 & BLE 5.4		FCM260S	
WLAN Protocol	IEEE 802.11 b/g/n/ax		
Wi-Fi Frequency Band	2.4 GHz		
2.4 GHz Channel Bandwidth	20 MHz		
Wi-Fi Modulation Mode	DBPSK, DQPSK, CCK, BPSK, QPSK, 16QAM, 64QAM, DCM		
Encryption Mode	WPA/WPA2/WPA3		
Wi-Fi Operating Mode	AP/STA		
Bluetooth Protocol	BLE 5.4		
Antenna	× 1 (PCB antenna/1 st generation RF coaxial connector/pin antenna) (optional)		
MCU Core	ARM Cortex-M4 (up to 180 MHz)		
SRAM	672 KB		
Flash	8 MB		
PSRAM Expansion (optional)	8 MB		
Dimensions	20.0 mm × 18.0 mm × 2.6 mm		
Weight	TBD		
Temperature Range			
Operating Temperature Range	-40 °C to +85 °C		
Storage Temperature Range	-45 °C to +95 °C		
Certifications			

Regulatory (Planning)

Europe: CE
America: FCC
Canada: IC
China: SRRC
Japan: TELEC
Australia/New Zealand: RCM

Interfaces			
Interfaces ^①	35 GPIOs (can be multiplexed as UART, SPI, I2C, SDIO, I2S, PWM, ADC, DAC, SSI, etc.)		
Electrical Features			
Power Supply Voltage	1.71–3.63 V, typ. 3.3 V		
Bluetooth Performance			
		Receiver Sensitivity	Transmit Power
BLE	1 Mbps	-96 dBm ±2 dB	≤ 17 dBm
	2 Mbps	-93 dBm ±2 dB	≤ 17 dBm
	500 kbps	-102.5 dBm ±2 dB	≤ 17 dBm
	125 kbps	-107 dBm ±2 dB	≤ 17 dBm

Ordering Code	Flash	SRAM	Transmit Power	Operating Temperature Range	Antenna	Development Board (Only for Debugging)
FCM260SAAMD-1X-08	8 MB	672 KB	≤ 17 dBm	-40 °C to +85 °C	1 st generation RF coaxial connector	FCM260SAATB-1X-08*
FCM260SAAMD-0L-08*	8 MB	672 KB	≤ 17 dBm	-40 °C to +85 °C	Pin antenna	FCM260SAATB-0L-08*
FCM260SAAMD-0P-08	8 MB	672 KB	≤ 17 dBm	-40 °C to +85 °C	PCB antenna	FCM260SAATB-0P-08

NOTE:

- ①: See hardware design manual for details of the module interfaces.
- *: Under development.